



DOCKET: CU-2417

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application: Takahiro IJIMA et al.]

Serial No.: 09/736,864]

Filed: December 14, 2000]

For: INTERCONNECTION SUBSTRATE]
HAVING METAL COLUMNS COVERED BY A]
RESIN FILM AND MANUFACTURING]
METHOD THEREOF]

GRP ART UNIT : 2815

Ex.: CHU, C.

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*Fig 10 Drawing
Changes*

*2/12/03
Shm th*

Certification under 37 C.F.R. §1.8(a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with The United States Postal Service with sufficient postage as first class mail in an envelope addressed to The Commissioner for Patents, Washington, D.C. 20231 on January 30, 2003.

Vangelis Economou
Vangelis Economou

Commissioner for Patents
Washington, D.C. 20231

**RETRANSMITTAL OF CORRECTED DRAWINGS
FOR EXAMINER'S APPROVAL**

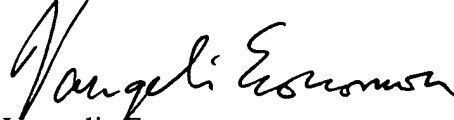
Sir:

Attached please find copies of drawing Fig. 2A (1 sheet), indicating by red ink the drawing correction for which the approval of the Examiner is respectfully requested. The drawing corrections have been requested by the Examiner in the Official Action dated June 25, 2002, and were disapproved when earlier submitted.

The identical changes have been made in respect of drawing Fig. 2A, that is, the lead line for the electrode 107 has been extended to indicate the correct element.

No new matter has been added to the drawings. The drawing figures are substantively identical to the drawings filed with the original application documents.

Respectfully submitted,



Vangelis Economou
Registration No. 32,341
Ladas & Parry
Attorneys for Applicant
224 South Michigan Avenue
Suite 1200
Chicago, Illinois 60604

January 30, 2003

Telephone: (312) 427-1300
Facsimile: (312) 427-6663